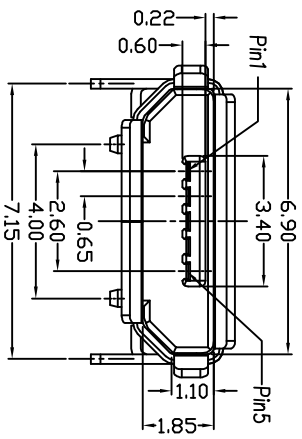
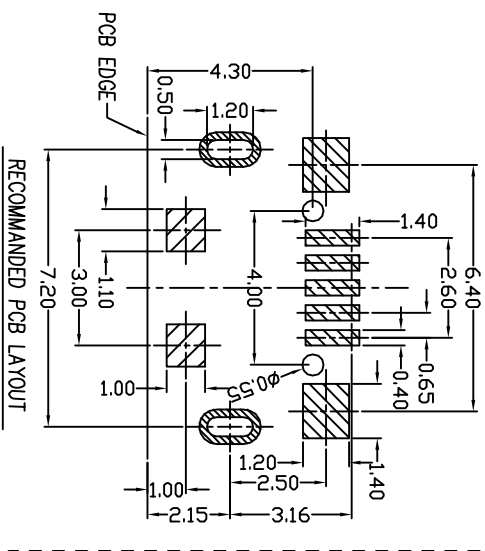
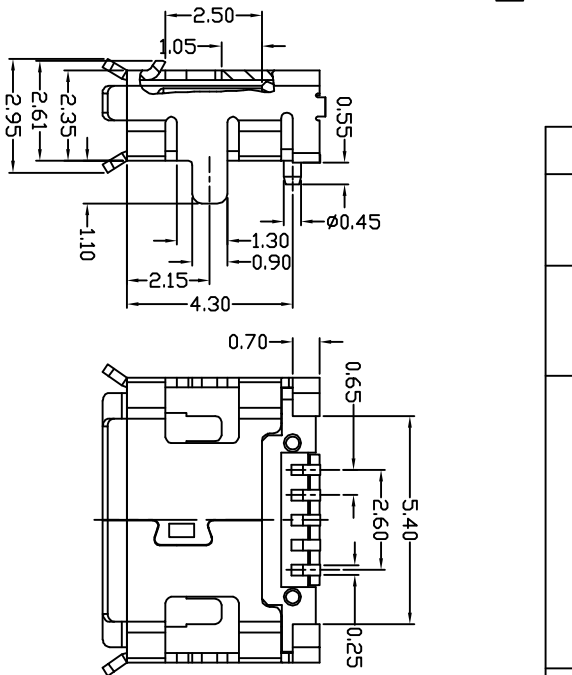
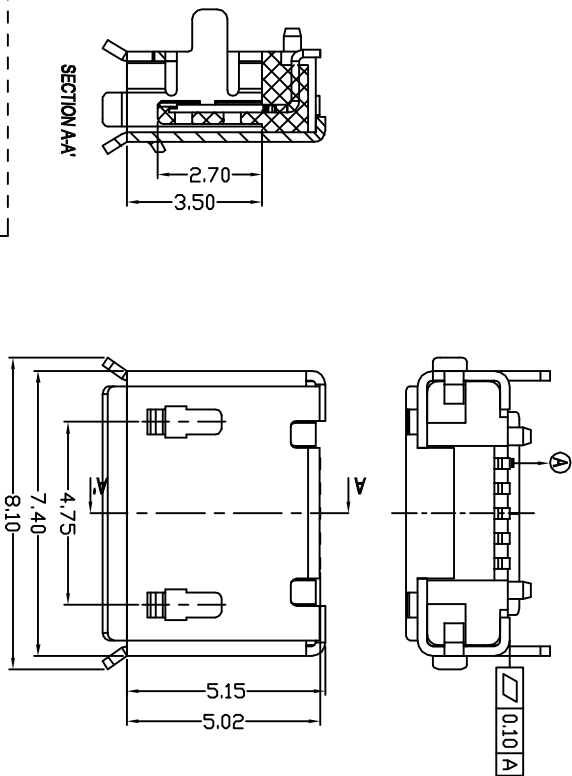


REV.	EQN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



- Notes:
1. Materials:
    - 1.1 Housing: High temperature thermoplastic with g.f; UL94 v-0.
    - 1.2 Contact: copper alloy, t=0.20mm.
    - 1.3 Shell: copper alloy, t=0.25mm.
  2. Specifications:
    - 2.1. Current rating: 1 A Max.
    - 2.2. Dielectric withstanding voltage: 100 V(ac) for 1 min.
    - 2.3. Contact resistance: 50 mW Max.
    - 2.4. Insulation resistance: 100 MW Min.
    - 2.5. Total mating force: 3.57 KgF Max.
    - 2.6. Total unmating force: 1.0 KgF Min 0.81~2.05 KgF Min. after 10000 insertion/extraction cycles
    - 2.7. Temperature range: -30°C~+80°C

PART NO: 1-MD05SMXXX-01		MATERIAL: SEE NOTE	
MODEL NO:		FINSH: SEE NOTE	
UNIT: mm	SIZE: A4	COLOR: SEE NOTE	
TOLERANCE UNSPECIFIED			
.x	±0.38	DR:	
.xx	±0.25	CHK:	
.xxx	±0.13	APP:	
ANG.	±2°		
TITLE: 深圳市精拓金电子有限公司		DWG NO: A055	
Micro usb SP/F B Type 插板7.2有导位有柱 (外壳加焊盘)		SCALE: 1:1	
		SHEET: 1/1	
		REV: A	

No.	Nome	Q'ty	Finish
3	Shell	1	N/A
2	Contact	5	N/A
1	Housing	1	N/A